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## (54) PRINTED-CIRCUIT BOARD AND WIRING PATTERN FORMATION METHOD

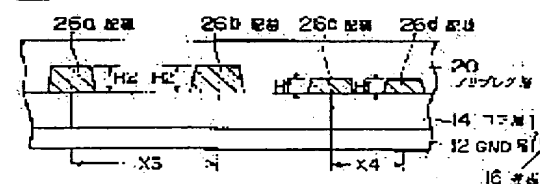
## (57)Abstract:

PROBLEM TO BE SOLVED: To provide a printed-circuit board for reducing crosstalk noise and at the same time densely performing wiring, and a wiring pattern formation method on the printed-wiring board.

SOLUTION: In a printed-circuit board 22, wirings 26a-26d are provided on a substrate 16 that is formed by laminating a core layer 14 on a GND layer 12, and is covered with a prepreg layer 20. Distance X3 between the wirings 26a and 26d (third and fourth wirings) are larger than normal, and also distance X4 between the wiring 26c and 26d (first and second wirings) is smaller than normal. While the wirings 26a and 26b are formed thickly (a thickness H2 is large in Fig. 1), the wirings 26c and 26d are formed thinly (a thickness H1 in Fig. 1 is small).

本発明の形態の一例に於けるプリント回路基板の部分断面図

22 プリント回路基板



## LEGAL STATUS

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